

Saga Electronics

Flipchip Fine Package (FFP)

NJR
NEWS

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Saga Electronics Co., Ltd.

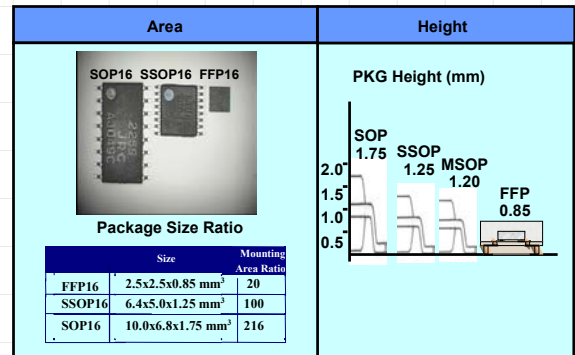
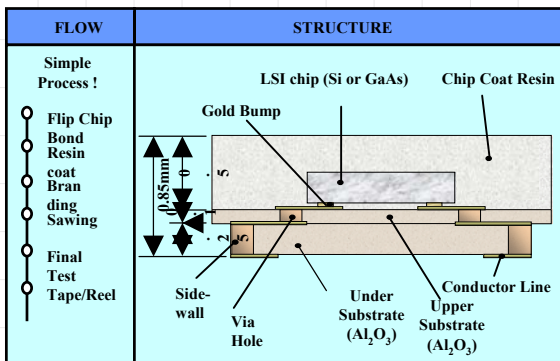
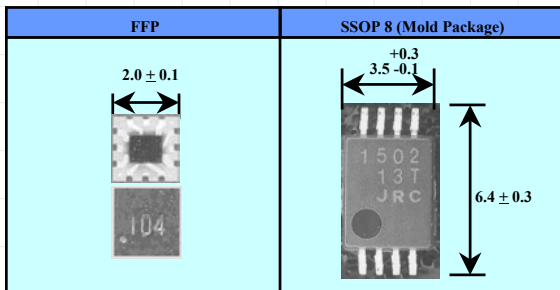
Saga Electronics FFP Packaging

Introducing our Flipchip Fine Package (FFP) from Saga Electronics!! A leader in IC packaging services. Saga Electronics is a subsidiary of New Japan Radio Co., Ltd. It is located in Saga Prefecture on Kyushu Island, Japan.

Saga Electronics provides IC packaging and testing services to OEMs. We integrated a very efficient production line which combines assembly, test, tape & reel packaging, and quality assurance for this service. Saga Electronics offers a quick turn-around time and utilizes its very efficient Just In Time (JIT) delivery.

Benefits

- Ceramic substrate and FCB technology to achieve RF performance. Ceramic substrate achieves high reliability.
- Small size and low profile reduces application's volume and weight.
- Solder fillet is visible for better mounting reliability.
- Lead less and fine outline tolerance reduce the gap between parts on PCB minimizing space requirement.
- Easy to get the suitable package size and pin count.
- MCM (Multi-Chip Module) application is available.



Mounting with 0.15mm gap between bottom pattern and PCB land



As reflow soldering, FFP package is aligned suitable position by self alignment



Check out our website! <http://www.sagaelec.co.jp>

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